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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

Axcelerator Family FPGAs

Leading-Edge Performance

- 350+ MHz System Performance
- 500+ MHz Internal Performance
- High-Performance Embedded FIFOs
- 700 Mb/s LVDS Capable I/Os

Specifications

- Up to 2 Million Equivalent System Gates
- Up to 684 I/Os
- Up to 10,752 Dedicated Flip-Flops
- Up to 295 kbits Embedded SRAM/FIFO
- Manufactured on Advanced 0.15 µm CMOS Antifuse Process Technology, 7 Layers of Metal

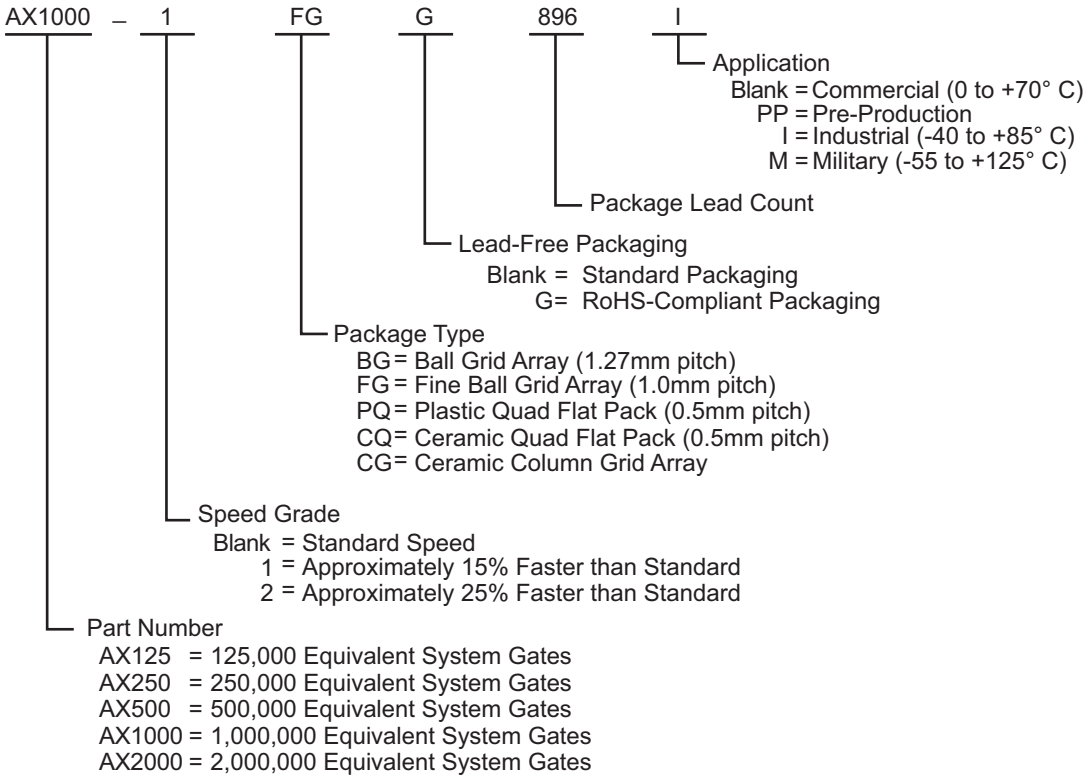
Features

- Single-Chip, Nonvolatile Solution
- Up to 100% Resource Utilization with 100% Pin Locking
- 1.5 V Core Voltage for Low Power
- Footprint Compatible Packaging
- Flexible, Multi-Standard I/Os:
  - 1.5 V, 1.8 V, 2.5 V, 3.3 V Mixed Voltage Operation
  - Bank-Selectable I/Os – 8 Banks per Chip
  - Single-Ended I/O Standards: LVTTL, LVCMOS, 3.3V PCI, and 3.3 V PCI-X
  - Differential I/O Standards: LVPECL and LVDS
  - Voltage-Referenced I/O Standards: GTL+, HSTL Class 1, SSTL2 Class 1 and 2, SSTL3 Class 1 and 2
  - Registered I/Os
  - Hot-Swap Compliant I/Os (except PCI)
  - Programmable Slew Rate and Drive Strength on Outputs
  - Programmable Delay and Weak Pull-Up/Pull-Down Circuits on Inputs
- Embedded Memory:
  - Variable-Aspect 4,608-bit RAM Blocks (x1, x2, x4, x9, x18, x36 Organizations Available)
  - Independent, Width-Configurable Read and Write Ports
  - Programmable Embedded FIFO Control Logic
- Segmentable Clock Resources
- Embedded Phase-Locked Loop:
  - 14-200 MHz Input Range
  - Frequency Synthesis Capabilities up to 1 GHz
- Deterministic, User-Controllable Timing
- Unique In-System Diagnostic and Debug Capability with Microsemi Silicon Explorer II
- Boundary-Scan Testing Compliant with IEEE Standard 1149.1 (JTAG)
- FuseLock™ Programming Technology Protects Against Reverse Engineering and Design Theft

Table 1 • Axcelerator Family Product Profile

Device	AX125	AX250	AX500	AX1000	AX2000
Capacity (in Equivalent System Gates)	125,000	250,000	500,000	1,000,000	2,000,000
Typical Gates	82,000	154,000	286,000	612,000	1,060,000
Modules					
Register (R-cells)	672	1,408	2,688	6,048	10,752
Combinatorial (C-cells)	1,344	2,816	5,376	12,096	21,504
Maximum Flip-Flops	1,344	2,816	5,376	12,096	21,504
Embedded RAM/FIFO					
Number of Core RAM Blocks	4	12	16	36	64
Total Bits of Core RAM	18,432	55,296	73,728	165,888	294,912
Clocks (Segmentable)					
Hardwired	4	4	4	4	4
Routed	4	4	4	4	4
PLLs	8	8	8	8	8
I/Os					
I/O Banks	8	8	8	8	8
Maximum User I/Os	168	248	336	516	684
Maximum LVDS Channels	84	124	168	258	342
Total I/O Registers	504	744	1,008	1,548	2,052
Package					
PQ		208	208		
BG				729	
FG	256, 324	256, 484	484, 676	484, 676, 896	896, 1152
CQ		208, 352	208, 352	352	256, 352
CG				624	624

Ordering Information



Device Resources

	User I/Os (Including Clock Buffers)				
Package	**AX125**	**AX250**	**AX500**	**AX1000**	**AX2000**
PQ208	–	115	115	–	–
CQ208	–	115	115	–	–
CQ256	–	–	–	–	136
FG256	138	138	–	–	–
FG324	168	–	–	–	–
CQ352	–	198	198	198	198
FG484	–	248	317	317	–
CG624	–	–	–	418	418
FG676	–	–	336	418	–
BG729	–	–	–	516	–
FG896	–	–	–	516	586
FG1152	–	–	–	–	684

Note: The FG256, FG324, and FG484 are footprint compatible with one another. The FG676, FG896, and FG1152 are also footprint compatible with one another.

Axcelerator Family Device Status

Axcelerator® Devices	Status
AX125	Production
AX250	Production
AX500	Production
AX1000	Production
AX2000	Production

Temperature Grade Offerings

Package	AX125	AX250	AX500	AX1000	AX2000
PQ208	–	C, I, M	C, I, M	–	–
CQ208	–	M	M	–	–
CQ256	–	–	–	–	M
FG256	C, I	C, I, M	–	–	–
FG324	C, I	–	–	–	–
CQ352	–	M	M	M	M
FG484	–	C, I, M	C, I, M	C, I, M	–
CG624	–	–	–	M	M
FG676	–	–	C, I, M	C, I, M	–
BG729	–	–	–	C, I, M	–
FG896	–	–	–	C, I, M	C, I, M
FG1152	–	–	–	–	C, I, M

C = Commercial

I = Industrial

M = Military

Speed Grade and Temperature Grade Matrix

Temperature Grade	Std	–1	–2
C	✓	✓	✓
I	✓	✓	✓
M	✓	✓	–

C = Commercial

I = Industrial

M = Military

Packaging Data

Refer to the following documents located on the Microsemi SoC Products Group website for additional packaging information.

- Package Mechanical Drawings
- Package Thermal Characteristics and Weights
- Hermatic Package Mechanical Information

Contact your local Microsemi representative for device availability.

Table of Contents

1 – General Description

Axcelerator devices offer high performance at densities of up to two million equivalent system gates. Based upon the Microsemi AX architecture, Axcelerator has several system-level features such as embedded SRAM (with complete FIFO control logic), PLLs, segmentable clocks, chip-wide highway routing, and carry logic.

Device Architecture

AX architecture, derived from the highly-successful SX-A sea-of-modules architecture, has been designed for high performance and total logic module utilization (Figure 1-1). Unlike in traditional FPGAs, the entire floor of the Axcelerator device is covered with a grid of logic modules, with virtually no chip area lost to interconnect elements or routing.

Programmable Interconnect Element

The Axcelerator family uses a patented metal-to-metal antifuse programmable interconnect element that resides between the upper two layers of metal (Figure 1-2 on page 1-2). This completely eliminates the channels of routing and interconnect resources between logic modules (as implemented on traditional FPGAs) and enables the efficient sea-of-modules architecture. The antifuses are normally open circuit and, when programmed, form a permanent, passive, low-impedance connection, leading to the fastest signal propagation in the industry. In addition, the extremely small size of these interconnect elements gives the Axcelerator family abundant routing resources.

The very nature of Microsemi's nonvolatile antifuse technology provides excellent protection against design pirating and cloning (FuseLock technology). Typical cloning attempts are impossible (even if the security fuse is left unprogrammed) as no bitstream or programming file is ever downloaded or stored in the device. Reverse engineering is virtually impossible due to the difficulty of trying to distinguish between programmed and unprogrammed antifuses and also due to the programming methodology of antifuse devices (see "Security" on page 2-108).

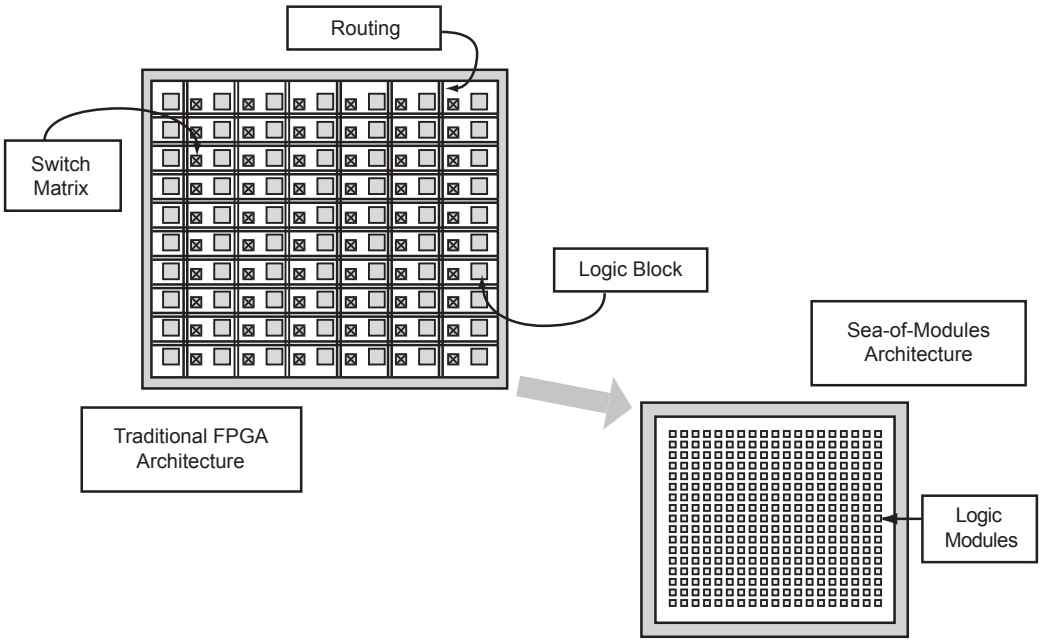


Figure 1-1 • **Sea-of-Modules Comparison**

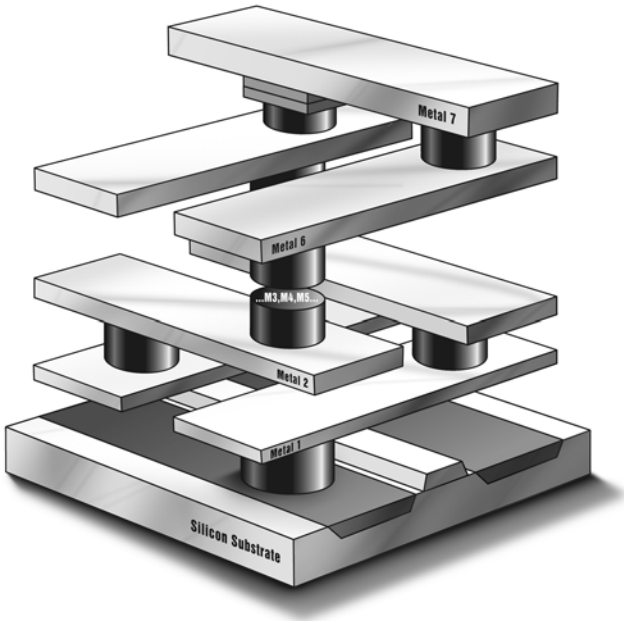


Figure 1-2 • **Axcelerator Family Interconnect Elements**

Logic Modules

Microsemi's Axcelerator family provides two types of logic modules: the register cell (R-cell) and the combinatorial cell (C-cell). The Axcelerator device can implement more than 4,000 combinatorial functions of up to five inputs (Figure 1-3).

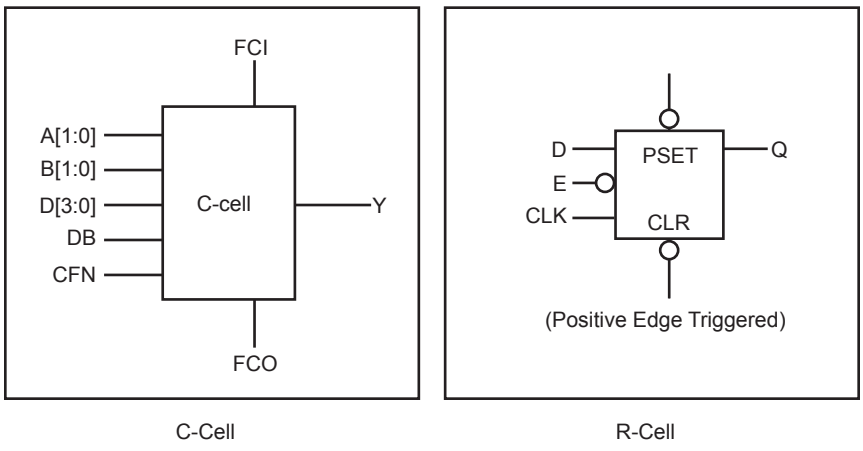


Figure 1-3 • **AX C-Cell and R-Cell**

The R-cell contains a flip-flop featuring asynchronous clear, asynchronous preset, and active-low enable control signals (Figure 1-3). The R-cell registers feature programmable clock polarity selectable on a register-by-register basis. This provides additional flexibility (e.g., easy mapping of dual-data-rate functions into the FPGA) while conserving valuable clock resources. The clock source for the R-cell can be chosen from the hardwired clocks, routed clocks, or internal logic.

Two C-cells, a single R-cell, two Transmit (TX), and two Receive (RX) routing buffers form a Cluster, while two Clusters comprise a SuperCluster (Figure 1-4). Each SuperCluster also contains an independent Buffer (B) module, which supports buffer insertion on high-fanout nets by the place-and-route tool, minimizing system delays while improving logic utilization.

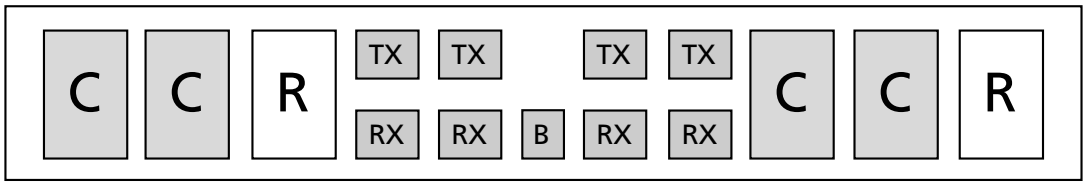


Figure 1-4 • **AX SuperCluster**

The logic modules within the SuperCluster are arranged so that two combinatorial modules are side-by-side, giving a C–C–R – C–C–R pattern to the SuperCluster. This C–C–R pattern enables efficient implementation (minimum delay) of two-bit carry logic for improved arithmetic performance (Figure 1-5 on page 1-3).

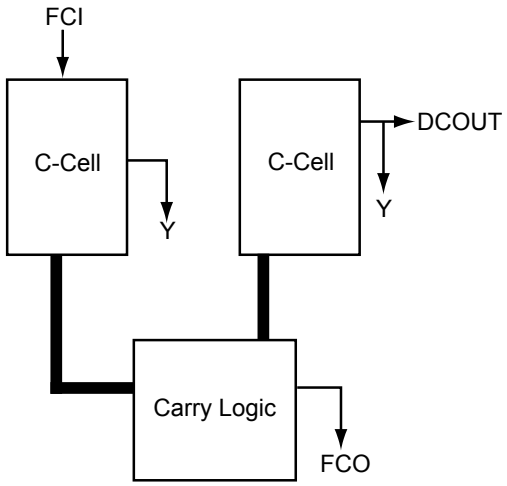


Figure 1-5 • **AX 2-Bit Carry Logic**

The AX architecture is fully fracturable, meaning that if one or more of the logic modules in a SuperCluster are used by a particular signal path, the other logic modules are still available for use by other paths.

At the chip level, SuperClusters are organized into core tiles, which are arrayed to build up the full chip. For example, the AX1000 is composed of a 3x3 array of nine core tiles. Surrounding the array of core tiles are blocks of I/O Clusters and the I/O bank ring (Table 1-1). Each core tile consists of an array of 336 SuperClusters and four SRAM blocks (176 SuperClusters and three SRAM blocks for the AX250).

Table 1-1 • **Number of Core Tiles per Device**

Device	Number of Core Tiles
AX125	1 regular tile
AX250	4 smaller tiles
AX500	4 regular tiles
AX1000	9 regular tiles
AX2000	16 regular tiles

The SRAM blocks are arranged in a column on the west side of the tile (Figure 1-6 on page 1-4).

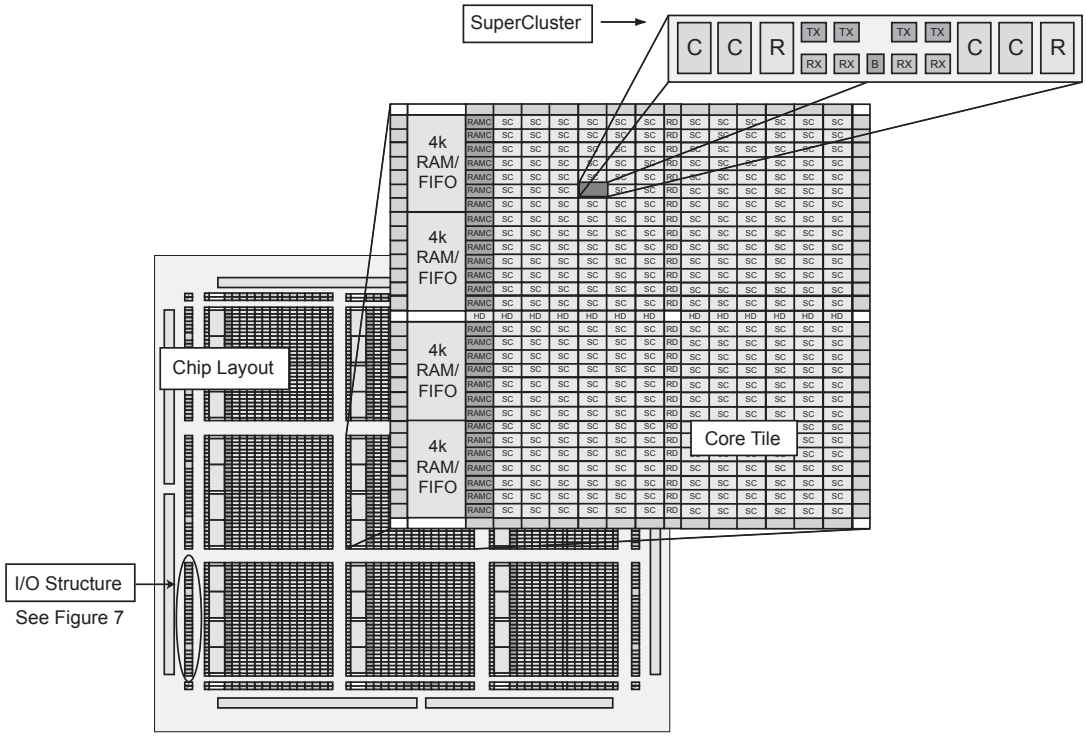


Figure 1-6 • **AX Device Architecture (AX1000 shown)**

Embedded Memory

As mentioned earlier, each core tile has either three (in a smaller tile) or four (in the regular tile) embedded SRAM blocks along the west side, and each variable-aspect-ratio SRAM block is 4,608 bits in size. Available memory configurations are: 128x36, 256x18, 512x9, 1kx4, 2kx2 or 4kx1 bits. The individual blocks have separate read and write ports that can be configured with different bit widths on each port. For example, data can be written in by eight and read out by one.

In addition, every SRAM block has an embedded FIFO control unit. The control unit allows the SRAM block to be configured as a synchronous FIFO without using core logic modules. The FIFO width and depth are programmable. The FIFO also features programmable ALMOST-EMPTY (AEMPTY) and ALMOST-FULL (AFULL) flags in addition to the normal EMPTY and FULL flags. In addition to the flag logic, the embedded FIFO control unit also contains the counters necessary for the generation of the read and write address pointers as well as control circuitry to prevent metastability and erroneous operation. The embedded SRAM/FIFO blocks can be cascaded to create larger configurations.

I/O Logic

The Axcelerator family of FPGAs features a flexible I/O structure, supporting a range of mixed voltages with its bank-selectable I/Os: 1.5V, 1.8V, 2.5V, and 3.3V. In all, Axcelerator FPGAs support at least 14 different I/O standards (single-ended, differential, voltage-referenced). The I/Os are organized into banks, with eight banks per device (two per side). The configuration of these banks determines the I/O standards supported (see "User I/Os" on page 2-11 for more information). All I/O standards are available in each bank.

Each I/O module has an input register (InReg), an output register (OutReg), and an enable register (EnReg) (Figure 1-7 on page 1-5). An I/O Cluster includes two I/O modules, four RX modules, two TX modules, and a buffer (B) module.

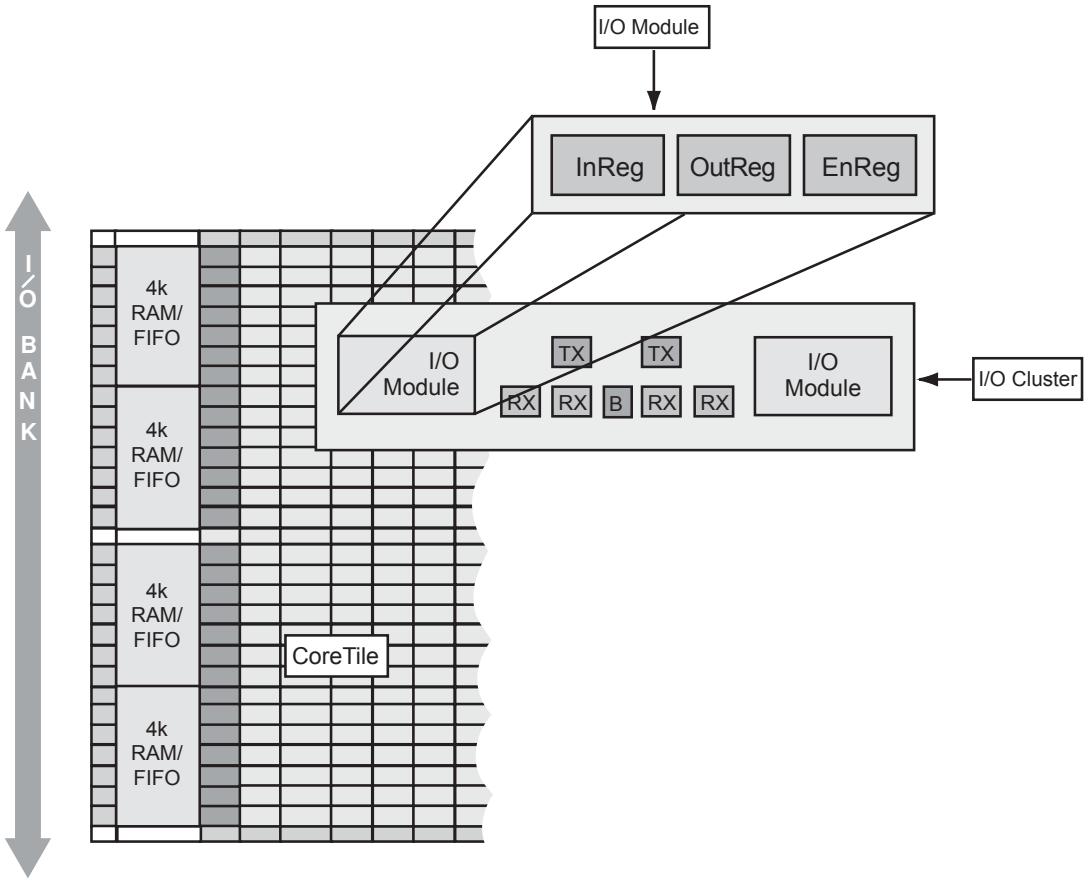


Figure 1-7 • **I/O Cluster Arrangement**

Routing

The AX hierarchical routing structure ties the logic modules, the embedded memory blocks, and the I/O modules together (Figure 1-8 on page 1-6). At the lowest level, in and between SuperClusters, there are three local routing structures: FastConnect, DirectConnect, and CarryConnect routing. DirectConnects provide the highest performance routing inside the SuperClusters by connecting a C-cell to the adjacent R-cell. DirectConnects do not require an antifuse to make the connection and achieve a signal propagation time of less than 0.1 ns.

FastConnects provide high-performance, horizontal routing inside the SuperCluster and vertical routing to the SuperCluster immediately below it. Only one programmable connection is used in a FastConnect path, delivering a maximum routing delay of 0.4 ns.

CarryConnects are used for routing carry logic between adjacent SuperClusters. They connect the FCO output of one two-bit, C-cell carry logic to the FCI input of the two-bit, C-cell carry logic of the SuperCluster below it. CarryConnects do not require an antifuse to make the connection and achieve a signal propagation time of less than 0.1 ns.

The next level contains the core tile routing. Over the SuperClusters within a core tile, both vertical and horizontal tracks run across rows or columns, respectively. At the chip level, vertical and horizontal tracks extend across the full length of the device, both north-to-south and east-to-west. These tracks are composed of highway routing that extend the entire length of the device (segmented at core tile boundaries) as well as segmented routing of varying lengths.

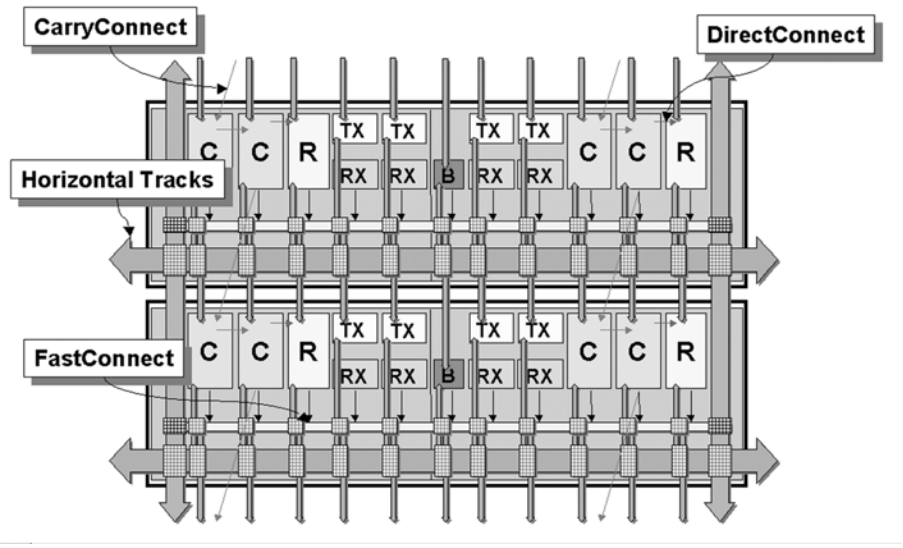


Figure 1-8 • **AX Routing Structures**

Global Resources

Each family member has three types of global signals available to the designer: HCLK, CLK, and GCLR/GPSET. There are four hardwired clocks (HCLK) per device that can directly drive the clock input of each R-cell. Each of the four routed clocks (CLK) can drive the clock, clear, preset, or enable pin of an R-cell or any input of a C-cell (Figure 1-3 on page 1-2).

Global clear (GCLR) and global preset (GPSET) drive the clear and preset inputs of each R-cell as well as each I/O Register on a chip-wide basis at power-up.

Each HCLK and CLK has an associated analog PLL (a total of eight per chip). Each embedded PLL can be used for clock delay minimization, clock delay adjustment, or clock frequency synthesis. The PLL is capable of operating with input frequencies ranging from 14 MHz to 200 MHz and can generate output frequencies between 20 MHz and 1 GHz. The clock can be either divided or multiplied by factors ranging from 1 to 64. Additionally, multiply and divide settings can be used in any combination as long as the resulting clock frequency is between 20 MHz and 1 GHz. Adjacent PLLs can be cascaded to create complex frequency combinations.

The PLL can be used to introduce either a positive or a negative clock delay of up to 3.75 ns in 250 ps increments. The reference clock required to drive the PLL can be derived from three sources: external input pad (either single-ended or differential), internal logic, or the output of an adjacent PLL.

Low Power (LP) Mode

The AX architecture was created for high-performance designs but also includes a low power mode (activated via the LP pin). When the low power mode is activated, I/O banks can be disabled (inputs disabled, outputs tristated), and PLLs can be placed in a power-down mode. All internal register states are maintained in this mode. Furthermore, individual I/O banks can be configured to opt out of the LP mode, thereby giving the designer access to critical signals while the rest of the chip is in low power mode.

The power can be further reduced by providing an external voltage source (V_{PUMP}) to the device to bypass the internal charge pump (See "Low Power Mode" on page 2-106 for more information).

Design Environment

The Axcelerator family of FPGAs is fully supported by both Microsemi's Libero® Integrated Design Environment and Designer FPGA Development software. Libero IDE is an integrated design manager that seamlessly integrates design tools while guiding the user through the design flow, managing all design and log files, and passing necessary design data among tools. Additionally, Libero IDE allows users to integrate both schematic and HDL synthesis into a single flow and verify the entire design in a single environment (see the *Libero IDE Flow* diagram located on the Microsemi SoC Products Group website). Libero IDE includes Synplify® Actel Edition (AE) from Synplicity®, ViewDraw® AE from Mentor Graphics®, Model*Sim*® HDL Simulator from Mentor Graphics, WaveFormer Lite™ AE from SynaptiCAD®, and Designer software from Microsemi.

Designer software is a place-and-route tool and provides a comprehensive suite of backend support tools for FPGA development. The Designer software includes the following:

- Timer – a world-class integrated static timing analyzer and constraints editor which support timing-driven place-and-route
- NetlistViewer – a design netlist schematic viewer
- ChipPlanner – a graphical floorplanner viewer and editor
- SmartPower – allows the designer to quickly estimate the power consumption of a design
- PinEditor – a graphical application for editing pin assignments and I/O attributes
- I/O Attribute Editor – displays all assigned and unassigned I/O macros and their attributes in a spreadsheet format

With the Designer software, a user can lock the design pins before layout while minimally impacting the results of place-and-route. Additionally, Microsemi's back-annotation flow is compatible with all the major simulators and the simulation results can be cross-probed with Silicon Explorer II, Microsemi's integrated verification and logic analysis tool. Another tool included in the Designer software is the SmartGen core generator, which easily creates popular and commonly used logic functions for implementation into your schematic or HDL design.

Designer software is compatible with the most popular FPGA design entry and verification tools from EDA vendors, such as Mentor Graphics, Synplicity, Synopsys, and Cadence Design Systems. The Designer software is available for both the Windows and UNIX operating systems.

Programming

Programming support is provided through Silicon Sculptor II, a single-site programmer driven via a PC-based GUI. In addition, BP Microsystems offers multi-site programmers that provide qualified support for Microsemi devices. Factory programming is available for high-volume production needs.

In-System Diagnostic and Debug Capabilities

The Axcelerator family of FPGAs includes internal probe circuitry, allowing the designer to dynamically observe and analyze any signal inside the FPGA without disturbing normal device operation (Figure 1-9).

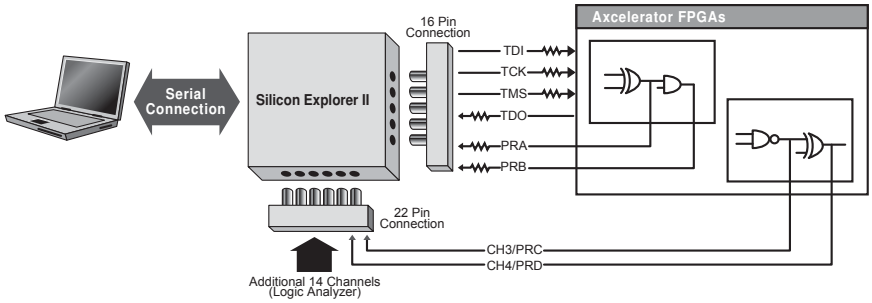


Figure 1-9 • **Probe Setup**

Up to four individual signals can be brought out to dedicated probe pins (PRA/B/C/D) on the device. The probe circuitry is accessed and controlled via Silicon Explorer II, Microsemi's integrated verification and logic analysis tool that attaches to the serial port of a PC and communicates with the FPGA via the JTAG port (See "Silicon Explorer II Probe Interface" on page 2-109).

Summary

Microsemi's Axcelerator family of FPGAs extends the successful SX-A architecture, adding embedded RAM/FIFOs, PLLs, and high-speed I/Os. With the support of a suite of robust software tools, design engineers can incorporate high gate counts and fixed pins into an Axcelerator design yet still achieve high performance and efficient device utilization.

Related Documents

Application Notes

Simultaneous Switching Noise and Signal Integrity
http://www.microsemi.com/soc/documents/SSN_AN.pdf
Axcelerator Family PLL and Clock Management
http://www.microsemi.com/soc/documents/AX_PLL_AN.pdf
Implementation of Security in Actel Antifuse FPGAs
http://www.microsemi.com/soc/documents/Antifuse_Security_AN.pdf

User's Guides and Manuals

Antifuse Macro Library Guide
http://www.microsemi.com/soc/documents/libguide_UG.pdf
SmartGen, FlashROM, Analog System Builder, and Flash Memory System Builder
http://www.microsemi.com/soc/documents/genguide_ug.pdf
Silicon Sculptor II User's Guide
http://www.microsemi.com/soc/documents/silisculptII_sculpt3_ug.pdf

White Paper

Design Security in Nonvolatile Flash and Antifuse FPGAs
http://www.microsemi.com/soc/documents/DesignSecurity_WP.pdf
Understanding Actel Antifuse Device Security
http://www.microsemi.com/soc/documents/DesignSecurity_WP.pdf

Miscellaneous

Libero IDE flow diagram
http://www.microsemi.com/soc/products/tools/libero/flow.html

2 – Detailed Specifications

Operating Conditions

Table 2-1 lists the absolute maximum ratings of Axcelerator devices. Stresses beyond the ratings may cause permanent damage to the device. Exposure to Absolute Maximum rated conditions for extended periods may affect device reliability. Devices should not be operated outside the recommendations in Table 2-2.

Table 2-1 • **Absolute Maximum Ratings**

Symbol	Parameter	Limits	Units
VCCA	DC Core Supply Voltage	–0.3 to 1.7	V
VCCI	DC I/O Supply Voltage	–0.3 to 3.75	V
VREF	DC I/O Reference Voltage	–0.3 to 3.75	V
VI	Input Voltage	–0.5 to 4.1	V
VO	Output Voltage	–0.5 to 3.75	V
TSTG	Storage Temperature	–60 to +150	°C
VCCDA*	Supply Voltage for Differential I/Os	–0.3 to 3.75	V

*Note: * Should be the maximum of all VCCI.*

Table 2-2 • **Recommended Operating Conditions**

Parameter Range	Commercial	Industrial	Military	Units
Ambient Temperature (T_A)[1]	0 to +70	–40 to +85	–55 to +125	°C
1.5 V Core Supply Voltage	1.425 to 1.575	1.425 to 1.575	1.425 to 1.575	V
1.5 V I/O Supply Voltage	1.425 to 1.575	1.425 to 1.575	1.425 to 1.575	V
1.8 V I/O Supply Voltage	1.71 to 1.89	1.71 to 1.89	1.71 to 1.89	V
2.5 V I/O Supply Voltage	2.375 to 2.625	2.375 to 2.625	2.375 to 2.625	V
3.3 V I/O Supply Voltage	3.0 to 3.6	3.0 to 3.6	3.0 to 3.6	V
VCCDA Supply Voltage	3.0 to 3.6	3.0 to 3.6	3.0 to 3.6	V
VPUMP Supply Voltage	3.0 to 3.6	3.0 to 3.6	3.0 to 3.6	V

Notes:

1. *Ambient temperature (T_A) is used for commercial and industrial grades; case temperature (T_C) is used for military grades.*
2. *T_J max = 125°C*

Power-Up/Down Sequence

All Axcelerator I/Os are tristated during power-up until normal device operating conditions are reached, when I/Os enter user mode. VCCDA should be powered up before (or coincidentally with) VCCA and VCCI to ensure the behavior of user I/Os at system start-up. Conversely, VCCDA should be powered down after (or coincidentally with) VCCA and VCCI. Note that VCCI and VCCA can be powered up in any sequence with respect to each other, provided the requirement with respect to VCCDA is satisfied.

Calculating Power Dissipation

Table 2-3 • **Standby Current**

Device	Temperature	ICCA	ICCDA	ICCBANK		ICCPLL	ICCCP[1]		IIH, IIL, IOZ[2]	Units
		Standby Current (Core)	Standby Current, Differential I/O	Standby Current per I/O Bank		Standby Current per PLL	Standby Current, Charge Pump			
				2.5 V VCCI	3.3 V VCCI		Active	Bypassed Mode		
AX125	Typical at 25°C	1.5	1.5	0.2	0.3	0.2	0.3	0.01	±0.01	mA
	70°C	15	6	0.5	0.75	1	0.4	0.01	±0.01	mA
	85°C	25	6	0.6	0.8	1	0.4	0.2	±0.01	mA
	125°C	50	8	1	1.5	2	0.4	0.5	±0.01	mA
AX250	Typical at 25°C	1.5	1.4	0.25	0.4	0.2	0.3	0.01	±0.01	mA
	70°C	30	7	0.8	0.9	1	0.4	0.01	±0.01	mA
	85°C	40	7	0.8	1	1	0.4	0.2	±0.01	mA
	125°C	70	9	1.3	1.8	2	0.4	0.5	±0.01	mA
AX500	Typical at 25°C	5	1.4	0.4	0.75	0.2	0.3	0.01	±0.01	mA
	70°C	60	7	1	1.5	1	0.4	0.01	±0.01	mA
	85°C	80	7	1	1.9	1	0.4	0.2	±0.01	mA
	125°C	180	9	1.75	2.5	1.5	0.4	0.5	±0.01	mA
AX1000	Typical at 25°C	7.5	1.5	0.5	1.25	0.2	0.3	0.01	±0.01	mA
	70°C	80	8	1.5	3	1	0.4	0.01	±0.01	mA
	85°C	120	8	1.5	3.4	1	0.4	0.2	±0.01	mA
	125°C	200	10	3	4	1.5	0.4	0.5	±0.01	mA
AX2000	Typical at 25°C	20	1.6	0.7	1.5	0.2	0.3	0.01	±0.01	mA
	70°C	160	10	2	7	1	0.4	0.01	±0.01	mA
	85°C	200	10	3	8	1	0.4	0.2	±0.01	mA
	125°C	500	15	4	10	1.5	0.4	0.5	±0.01	mA

Notes:

1. *ICCCP Active is the ICCDA or the Internal Charge Pump current. ICCCP Bypassed mode is the External Charge Pump current IIH (VPUMP pin).*
2. *IIH, IIL, or IOZ values are measured with inputs at the same level as VCCI for IIH and GND for IIL and IOZ.*

Table 2-4 • **Default CLOAD/VCCI**

	C_{LOAD} (pF)	VCCI (V)	PLOAD (mw/MHz)	P10 (mw/MHz)	PI/O (mW/MHz)*
Single-Ended without VREF					
LVTTL 24 mA High Slew	35	3.3	381.2	267.5	648.7
LVTTL 16 mA High Slew	35	3.3	381.2	225.1	606.3
LVTTL 12 mA High Slew	35	3.3	381.2	165.9	547.1
LVTTL 8 mA High Slew	35	3.3	381.2	130.3	511.5
LVTTL 24 mA Low Slew	35	3.3	381.2	169.2	550.4
LVTTL 16 mA Low Slew	35	3.3	381.2	150.8	532.0
LVTTL 12 mA Low Slew	35	3.3	381.2	138.6	519.8
LVTTL 8 mA Low Slew	35	3.3	381.2	118.7	499.9
LVCMOS – 25	35	2.5	218.8	148.0	366.8
LVCMOS – 18	35	1.8	113.4	73.4	186.8
LVCMOS – 15 (JESD8-11)	35	1.5	78.8	49.5	128.3
PCI	10	3.3	108.9	218.5	327.4
PCI-X	10	3.3	108.9	162.9	271.8
Single-Ended with VREF					
HSTL-I	20	1.5	–	40.9	40.9
SSTL2-I	30	2.5	–	171.2	171.2
SSTL2-II	30	2.5	–	147.8	147.8
SSTL3-I	30	3.3	–	327.2	327.2
SSTL3-II	30	3.3	–	288.4	288.4
GTLP – 25	10	2.5	–	61.5	61.5
GTLP – 33	10	3.3	–	68.5	68.5
Differential					
LVPECL – 33	N/A	3.3	–	260.6	260.6
LVDS – 25	N/A	2.5	–	145.8	145.8

Note: $*P_{I/O} = P10 + C_{LOAD} * VCCI^2$

Table 2-5 • **Different Components Contributing to the Total Power Consumption in Axcelerator Devices**

Component	Definition	Device Specific Value (in µW/MHz)				
		AX125	AX250	AX500	AX1000	AX2000
P1	Core tile HCLK power component	33	49	71	130	216
P2	R-cell power component	0.2	0.2	0.2	0.2	0.2
P3	HCLK signal power dissipation	4.5	4.5	9	13.5	18
P4	Core tile RCLK power component	33	49	71	130	216
P5	R-cell power component	0.3	0.3	0.3	0.3	0.3
P6	RCLK signal power dissipation	6.5	6.5	13	19.5	26
P7	Power dissipation due to the switching activity on the R-cell	1.6	1.6	1.6	1.6	1.6
P8	Power dissipation due to the switching activity on the C-cell	1.4	1.4	1.4	1.4	1.4
P9	Power component associated with the input voltage	10	10	10	10	10
P10	Power component associated with the output voltage	See table Per pin contribution				
P11	Power component associated with the read operation in the RAM block	25	25	25	25	25
P12	Power component associated with the write operation in the RAM block	30	30	30	30	30
P13	Core PLL power component	1.5	1.5	1.5	1.5	1.5

Ptotal = Pdc + Pac

P_{dc} = ICCA * VCCA

P_{ac} = $P_{HCLK} + P_{CLK} + P_{R\text{-}cells} + P_{C\text{-}cells} + P_{inputs} + P_{outputs} + P_{memory} + P_{PLL}$

P_{HCLK} = (P1 + P2 * s + P3 * sqrt[s]) * Fs

s = the number of R-cells clocked by this clock

Fs = the clock frequency

PCLK = (P4 + P5 * s + P6 * sqrt[s]) * Fs

s = the number of R-cells clocked by this clock

Fs = the clock frequency

PR-cells = P7 * ms * Fs

ms = the number of R-cells switching at each Fs cycle

Fs = the clock frequency

PC-cells = P8 * mc * Fs

mc = the number of C-cells switching at each Fs cycle

Fs = the clock frequency

Pinputs = P9 * pi * Fpi

pi = the number of inputs

F_{pi} = the average input frequency

Poutputs = PI/O * po * Fpo

C_{load} = the output load (technology dependent)
VCCI = the output voltage (technology dependent)
po = the number of outputs
F_{po} = the average output frequency

Pmemory = P11 * Nblock * FRCLK + P12 * Nblock * FWCLK

N_{block} = the number of RAM/FIFO blocks (1 block = 4k)
F_{RCLK} = the read-clock frequency of the memory
F_{WCLK} = the write-clock frequency of the memory

PPLL = P13 * FCLK

F_{RefCLK} = the clock frequency of the clock input of the PLL
F_{CLK} = the clock frequency of the first clock output of the PLL

Power Estimation Example

This example employs an AX1000 shift-register design with 1,080 R-cells, one C-cell, one reset input, and one LVTTL 12 mA output, with high slew.

This design uses one HCLK at 100 MHz.

ms = 1,080 (in a shift register - 100% of R-cells are toggling at each clock cycle)
Fs = 100 MHz
s = 1080
=> P_{HCLK} = (P1 + P2 * s + P3 * sqrt[s]) * Fs = 79 mW
and Fs = 100 MHz
=> $P_{R\text{-}cells}$ = P7 * ms * Fs = 173 mW
mc = 1 (1 C-cell in this shift-register)
and Fs = 100 MHz
=> $P_{C\text{-}cells}$ = P8 * mc * Fs = 0.14 mW
F_{pi} ~ 0 MHz
and pi= 1 (1 reset input => this is why F_{pi}=0)
=> P_{inputs} = P9 * pi * F_{pi} = 0 mW
F_{po} = 50 MHz
and po = 1
=> $P_{outputs}$ = $P_{I/O}$ * po * F_{po}= 27.10 mW
No RAM/FIFO in this shift-register
=> P_{memory} = 0 mW
No PLL in this shift-register
=> P_{PLL} = 0 mW
$P_{ac} = P_{HCLK} + P_{CLK} + P_{R\text{-}cells} + P_{C\text{-}cells} + P_{inputs} + P_{outputs} + P_{memory} + P_{PLL}$ = 276 mW
P_{dc} = 7.5mA * 1.5V = 11.25 mW
$P_{total} = P_{dc} + P_{ac}$ = 11.25 mW + 276mW = 290.30 mW

Thermal Characteristics

Introduction

The temperature variable in Microsemi's Designer software refers to the junction temperature, not the ambient temperature. This is an important distinction because dynamic and static power consumption cause the chip junction temperature to be higher than the ambient temperature. EQ 1 can be used to calculate junction temperature.

T_J = Junction Temperature = $\Delta T + T_a$

EQ 1

Where:

T_a = Ambient Temperature

ΔT = Temperature gradient between junction (silicon) and ambient

$\Delta T = \theta_{ja} * P$

EQ 2

Where:

P = Power

θ_{ja} = Junction to ambient of package. θ_{ja} numbers are located under Table 2-6 on page 2-7.

Package Thermal Characteristics

The device junction-to-case thermal characteristic is θ_{jc}, and the junction-to-ambient air characteristic is θ_{ja}. The thermal characteristics for θ_{ja} are shown with two different air flow rates. θ_{jc} values are provided for reference. The absolute maximum junction temperature is 125°C.

The maximum power dissipation allowed for commercial- and industrial-grade devices is a function of θ_{ja}. A sample calculation of the absolute maximum power dissipation allowed for an 896-pin FBGA package at commercial temperature and still air is as follows:

$$\text{Maximum Power Allowed} = \frac{\text{Max. junction temp. } (°C) - \text{Max. ambient temp. } (°C)}{\theta_{ja}(°C/W)} = \frac{125°C - 70°C}{13.6°C/W} = 4.04\ W$$

The maximum power dissipation allowed for Military temperature and Mil-Std 883B devices is specified as a function of θ_{jc}.

Table 2-6 • **Package Thermal Characteristics**

Package Type	Pin Count	θ_{jc}	θ_{ja} Still Air	θ_{ja} 1.0m/s	θ_{ja} 2.5m/s	Units
Chip Scale Package (CSP)	180	N/A	57.8	51.0	50	°C/W
Plastic Quad Flat Pack (PQFP)	208	8.0	26	23.5	20.9	°C/W
Plastic Ball Grid Array (PBGA)	729	2.2	13.7	10.6	9.6	°C/W
Fine Pitch Ball Grid Array (FBGA)	256	3.0	26.6	22.8	21.5	°C/W
Fine Pitch Ball Grid Array (FBGA)	324	3.0	25.8	22.1	20.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	484	3.2	20.5	17.0	15.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	676	3.2	16.4	13.0	12.0	°C/W
Fine Pitch Ball Grid Array (FBGA)	896	2.4	13.6	10.4	9.4	°C/W
Fine Pitch Ball Grid Array (FBGA)	1152	1.8	12.0	8.9	7.9	°C/W
Ceramic Quad Flat Pack (CQFP)[1]	208	2.0	22	19.8	18.0	°C/W
Ceramic Quad Flat Pack (CQFP)[1]	352	2.0	17.9	16.1	14.7	°C/W
Ceramic Column Grid Array (CCGA)[2]	624	6.5	8.9	8.5	8	°C/W

Notes:

1. *θ_{jc} for the 208-pin and 352-pin CQFP refers to the thermal resistance between the junction and the bottom of the package.*
2. *θ_{jc} for the 624-pin CCGA refers to the thermal resistance between the junction and the top surface of the package. Thermal resistance from junction to board (θ_{jb}) for CCGA 624 package is 3.4°C/W.*

Timing Characteristics

Axcelerator devices are manufactured in a CMOS process, therefore, device performance varies according to temperature, voltage, and process variations. Minimum timing parameters reflect maximum operating voltage, minimum operating temperature, and best-case processing. Maximum timing parameters reflect minimum operating voltage, maximum operating temperature, and worst-case processing. The derating factors shown in Table 2-7 should be applied to all timing data contained within this datasheet.

Table 2-7 • **Temperature and Voltage Timing Derating Factors (Normalized to Worst-Case Commercial, T_J = 70°C, VCCA = 1.425V)**

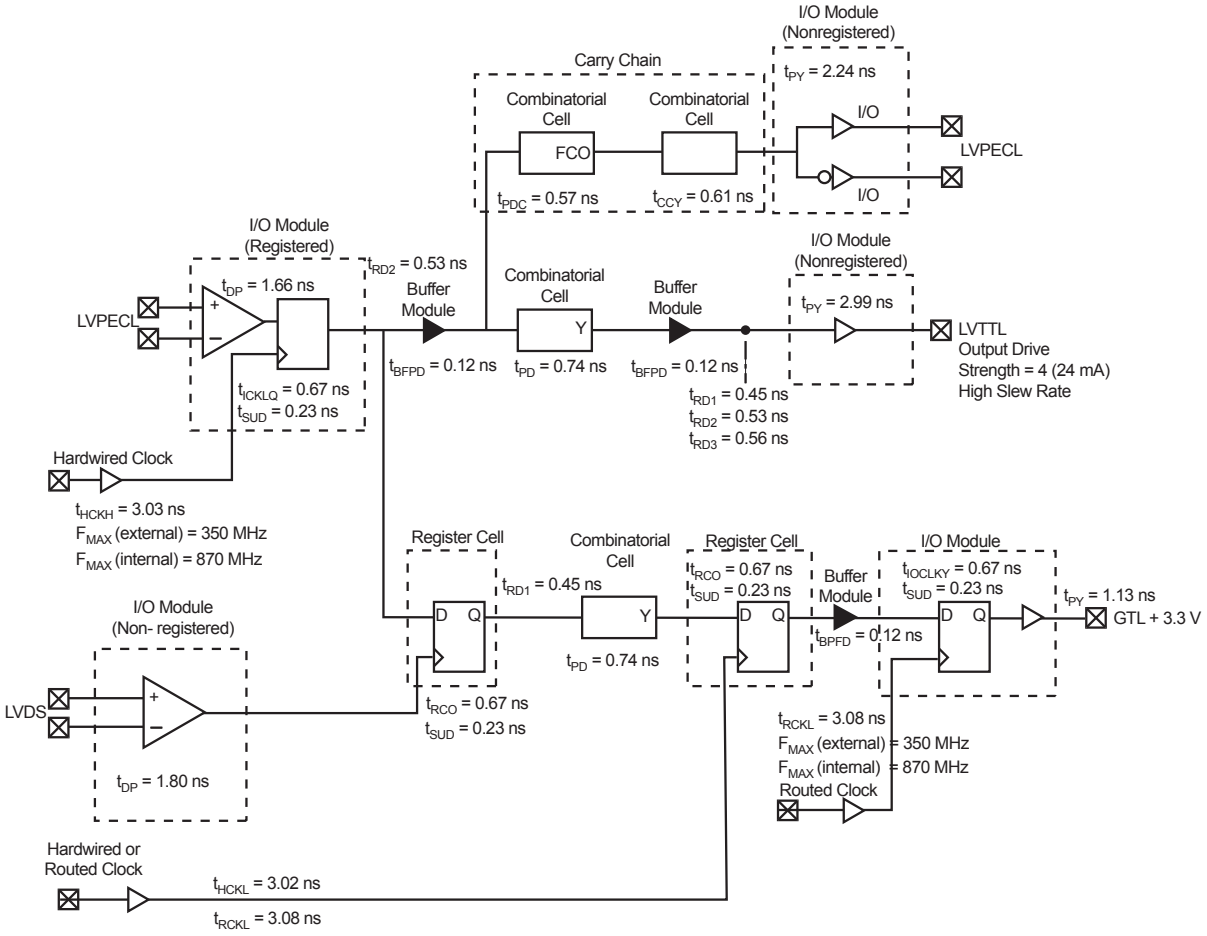
	Junction Temperature						
VCCA	–55°C	–40°C	0°C	25°C	70°C	85°C	125°C
1.4 V	0.83	0.86	0.91	0.96	1.02	1.05	1.15
1.425 V	0.82	0.84	0.90	0.94	1.00	1.04	1.13
1.5 V	0.78	0.80	0.85	0.89	0.95	0.98	1.07
1.575 V	0.74	0.76	0.81	0.85	0.90	0.94	1.02
1.6 V	0.73	0.75	0.80	0.84	0.89	0.92	1.01

Notes:

1. *The user can set the junction temperature in Designer software to be any integer value in the range of –55°C to 175°C.*
2. *The user can set the core voltage in Designer software to be any value between 1.4V and 1.6V.*

All timing numbers listed in this datasheet represent sample timing characteristics of Axcelerator devices. Actual timing delay values are design-specific and can be derived from the Timer tool in Microsemi's Designer software after place-and-route.

Timing Model



Note: Worst case timing data for the AX1000, –2 speed grade

Figure 2-1 • **Worst Case Timing Data**

Hardwired Clock – Using LVTTL 24 mA High Slew Clock I/O

External Setup

$= (t_{DP} + t_{RD2} + t_{SUD}) – t_{HCKL}$

$= (1.72 + 0.53 + 0.23) – 3.02 = –0.54$ ns

Clock-to-Out (Pad-to-Pad)

$= t_{HCKL} + t_{RCO} + t_{RD1} + t_{PY}$

$= 3.02 + 0.67 + 0.45 + 2.99 = 7.13$ ns

Routed Clock – Using LVTTL 24 mA High Slew Clock I/O

External Setup

$= (t_{DP} + t_{RD2} + t_{SUD}) – t_{RCKH}$

$= (1.72 + 0.53 + 0.23) – 3.13 = –0.65$ ns

Clock-to-Out (Pad-to-Pad)

$= t_{RCKH} + t_{RCO} + t_{RD1} + t_{PY}$

$= 3.13 + 0.67 + 0.45 + 3.03 = 7.24$ ns

I/O Specifications

Pin Descriptions

Supply Pins

GND **Ground**

Low supply voltage.

VCCA **Supply Voltage**

Supply voltage for array (1.5V). See "Operating Conditions" on page 2-1 for more information.

VCCIBx **Supply Voltage**

Supply voltage for I/Os. Bx is the I/O Bank ID – 0 to 7. See "Operating Conditions" on page 2-1 for more information.

VCCDA **Supply Voltage**

Supply voltage for the I/O differential amplifier and JTAG and probe interfaces. See "Operating Conditions" on page 2-1 for more information. VCCDA should be tied to 3.3V.

VCCPLA/B/C/D/E/F/G/H **Supply Voltage**

PLL analog power supply (1.5V) for internal PLL. There are eight in each device. VCCPLA supports the PLL associated with global resource HCLKA, VCCPLB supports the PLL associated with global resource HCLKB, etc. The PLL analog power supply pins should be connected to 1.5V whether PLL is used or not.

VCOMPLA/B/C/D/E/F/G/H **Supply Voltage**

Compensation reference signals for internal PLL. There are eight in each device. **VCOMPLA** supports the PLL associated with global resource HCLKA, VCOMPLE supports the PLL associated with global resource CLKE, etc. (see Figure 2-2 on page 2-9 for correct external connection to the supply). The VCOMPLX pins should be left floating if PLL is not used.

VPUMP **Supply Voltage (External Pump)**

In the low power mode, VPUMP will be used to access an external charge pump (if the user desires to bypass the internal charge pump to further reduce power). The device starts using the external charge pump when the voltage level on VPUMP reaches VIH[1]. In normal device operation, when using the internal charge pump, VPUMP should be tied to GND.

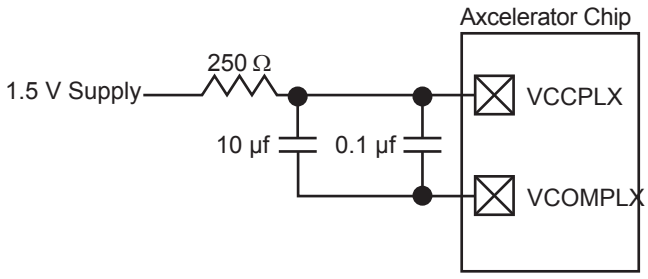


Figure 2-2 • **VCCPLX and VCOMPLX Power Supply Connect**

1. *When $V_{PUMP} = V_{IH}$, it shuts off the internal charge pump. See* ***"Low Power Mode" on page 2-106****.*

User-Defined Supply Pins

VREF **Supply Voltage**

Reference voltage for I/O banks. VREF pins are configured by the user from regular I/O pins; VREF pins are not in fixed locations. There can be one or more VREF pins in an I/O bank.

Global Pins

HCLKA/B/C/D **Dedicated (Hardwired) Clocks A, B, C and D**

These pins are the clock inputs for sequential modules or north PLLs. Input levels are compatible with all supported I/O standards. There is a P/N pin pair for support of differential I/O standards. Single-ended clock I/Os can only be assigned to the P side of a paired I/O. This input is directly wired to each R-cell and offers clock speeds independent of the number of R-cells being driven. When the HCLK pins are unused, it is recommended that they are tied to ground.

CLKE/F/G/H **Routed Clocks E, F, G, and H**

These pins are clock inputs for clock distribution networks or south PLLs. Input levels are compatible with all supported I/O standards. There is a P/N pin pair for support of differential I/O standards. Single-ended clock I/Os can only be assigned to the P side of a paired I/O. The clock input is buffered prior to clocking the R-cells. When the CLK pins are unused, Microsemi recommends that they are tied to ground.

JTAG/Probe Pins

PRA/B/C/D **Probe A, B, C and D**

The Probe pins are used to output data from any user-defined design node within the device (controlled with Silicon Explorer II). These independent diagnostic pins can be used to allow real-time diagnostic output of any signal path within the device. The pins' probe capabilities can be permanently disabled to protect programmed design confidentiality. The probe pins are of LVTTL output levels.

TCK **Test Clock**

Test clock input for JTAG boundary-scan testing and diagnostic probe (Silicon Explorer II).

TDI **Test Data Input**

Serial input for JTAG boundary-scan testing and diagnostic probe. TDI is equipped with an internal 10 kΩ pull-up resistor.

TDO **Test Data Output**

Serial output for JTAG boundary-scan testing.

TMS **Test Mode Select**

The TMS pin controls the use of the IEEE 1149.1 boundary-scan pins (TCK, TDI, TDO, TRST). TMS is equipped with an internal 10 kΩ pull-up resistor.

TRST **Boundary Scan Reset Pin**

The TRST pin functions as an active-low input to asynchronously initialize or reset the boundary scan circuit. The TRST pin is equipped with a 10 kΩ pull-up resistor.

Special Functions

LP **Low Power Pin**

The LP pin controls the low power mode of Axcelerator devices. The device is placed in the low power mode by connecting the LP pin to logic high. To exit the low power mode, the LP pin must be set Low. Additionally, the LP pin must be set Low during chip powering-up or chip powering-down operations. See "Low Power Mode" on page 2-106 for more details.

NC **No Connection**

This pin is not connected to circuitry within the device. These pins can be driven to any voltage or can be left floating with no effect on the operation of the device.

User I/Os[2]

Introduction

The Axcelerator family features a flexible I/O structure, supporting a range of mixed voltages (1.5 V, 1.8 V, 2.5 V, and 3.3 V) with its bank-selectable I/Os. Table 2-8 on page 2-12 contains the I/O standards supported by the Axcelerator family, and Table 2-10 on page 2-12 compares the features of the different I/O standards.

Each I/O provides programmable slew rates, drive strengths, and weak pull-up and weak pull-down circuits. The slew rate setting is effective for both rising and falling edges.

I/O standards, except 3.3 V PCI and 3.3 V PCI-X, are capable of hot insertion. 3.3 V PCI and 3.3 V PCI-X are 5 V tolerant with the aid of an external resistor.

The input buffer has an optional user-configurable delay element. The element can reduce or eliminate the hold time requirement for input signals registered within the I/O cell. The value for the delay is set on a bank-wide basis. Note that the delay WILL be a function of process variations as well as temperature and voltage changes.

Each I/O includes three registers: an input (InReg), an output (OutReg), and an enable register (EnReg). I/Os are organized into banks, and there are eight banks per device—two per side (Figure 2-6 on page 2-18). Each I/O bank has a common VCCI, the supply voltage for its I/Os.

For voltage-referenced I/Os, each bank also has a common reference-voltage bus, VREF. While VREF must have a common voltage for an entire I/O bank, its location is user-selectable. In other words, any user I/O in the bank can be selected to be a VREF.

The location of the VREF pin should be selected according to the following rules:

- Any pin that is assigned as a VREF can control a maximum of eight user I/O pad locations in each direction (16 total maximum) within the same I/O bank.
- I/O pad locations listed as no connects are counted as part of the 16 maximum. In many cases, this leads to fewer than eight user I/O package pins in each direction being controlled by a VREF pin.
- Dedicated I/O pins such as GND and VCCI are counted as part of the 16.
- The two user I/O pads immediately adjacent on each side of the VREF pin (four in total) may only be used as inputs. The exception is when there is a VCCI/GND pair separating the VREF pin and the user I/O pad location.
- The user does not need to assign VREF pins for OUTBUF and TRIBUF. VREF pins are needed only for input and bidirectional I/Os.

The differential amplifier supply voltage VCCDA should be connected to 3.3 V.

A user can gain access to the various I/O standards in three ways:

- Instantiate specific library macros that represent the desired specific standard.
- Use generic I/O macros and then use Designer's PinEditor to specify the desired I/O standards (please note that this is not applicable to differential standards).
- A combination of the first two methods.

Refer to the *I/O Features in Axcelerator Family Devices* application note and the *Antifuse Macro Library Guide* for more details.

2. *Do not use an external resister to pull the I/O above V_{CCI} for a higher logic "1" voltage level. The desired higher logic "1" voltage level will be degraded due to a small I/O current, which exists when the I/O is pulled up above V_{CCI}.*